

HIONIX

Advanced Thin Film Processing Services



THIN FILM TECHNOLOGY SOLUTIONS

Located in the Silicon Valley, Hionix Inc. has in-depth and extensive expertise in fabrication systems design, process development, and material analysis serving semiconductor, biomedical, photonics, AR/VR, MEMS, and other high-tech industries. Housed in a class 100 clean room, Hionix offers state of the art PVD and Furnace systems.

Capabilities of our Sputtering Systems

- DC Magnetron sputtering: faster metal and dielectric deposition
- Reactive sputtering available for Nitride, Carbide, and Oxide films
- Cosputtered films available for up to 3 targets
- RF sputtering to sputter dielectric and magnetic materials
- RF Bias for sputter etching and deposition with Bias
- Controlled substrate temperature: Depositions routinely below 80C. Depositions below 40C available
- Up to 6 different materials without vacuum breaks
- Degas and ICP chamber integration
- R&D and Production capabilities

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SERVICES AVAILABLE

PVD Thin Films

Hionix offers a large variety of materials in stock for thin film sputtering. Aluminum to Zirconium films available for substrates 25mm to 450mm.

TSV: Barrier and Seed w/High Step-Coverage

Hionix offers TSV coverage for many patterned structures for up to 7:1 Aspect Ratios.

Thermal Oxide

Hionix offers in house Wet and Dry Thermal oxidation services from 1KA-10KA thickness.

Wafer Bonding

Hionix offers wafer bonding up to 150mm. Silicon to silicon and glass to glass.

Environmental Testing

Hionix can test samples and devices in an environmental testing chamber. Offering temperature cycling from -73C to 190 C and humidity from 10 to 95%.

Silicon Wafers

Hionix can supply silicon or glass wafers from 25mm to 300mm diameter.

Nonstandard sized substrate services available

